

General Description

This planar stripe MOSFET has better characteristics, such as fast switching time, low on resistance, low gate charge and excellent avalanche characteristics. It is mainly suitable for DC/DC converters and switching mode power supplies.

FEATURES

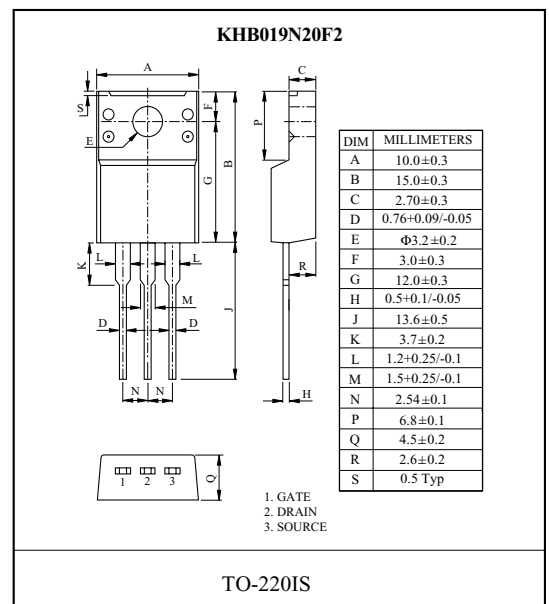
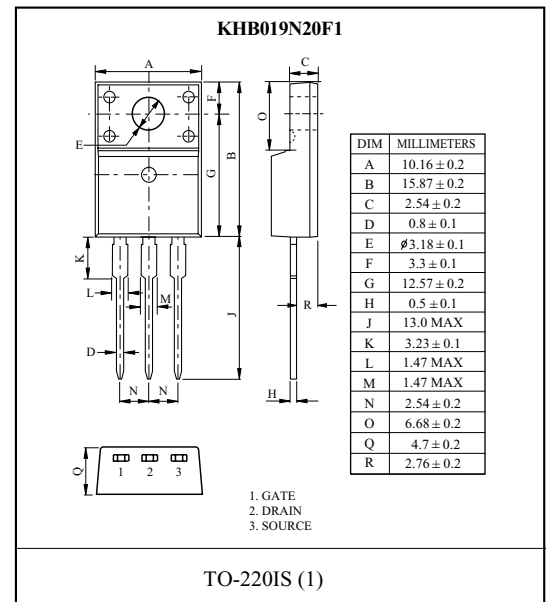
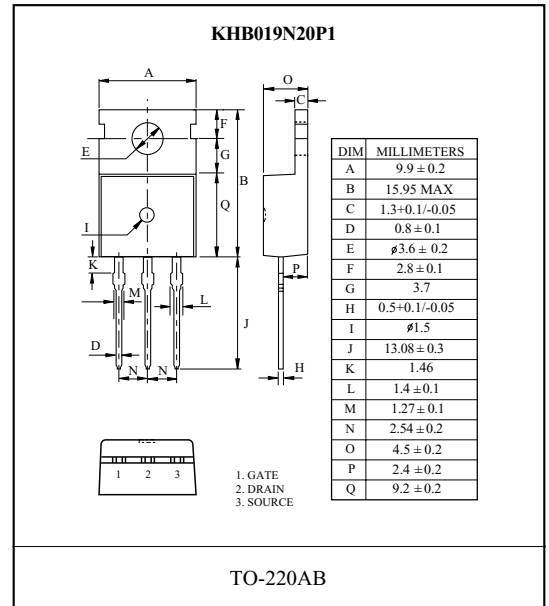
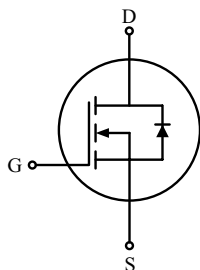
- $V_{DSS}=200V$, $I_D=19A$
- Drain-Source ON Resistance : $R_{DS(ON)}=0.18$ @ $V_{GS} = 10V$
- $Qg(\text{typ.})=35nC$

MAXIMUM RATING (Tc=25)

CHARACTERISTIC	SYMBOL	RATING		UNIT
		KHB019N20P1	KHB019N20F1 KHB019N20F2	
Drain-Source Voltage	V_{DSS}	200		V
Gate-Source Voltage	V_{GSS}	± 30		V
Drain Current	@T _C =25	19	19*	A
	@T _C =100	12.1	12.1*	
	Pulsed (Note1)	76	76*	
Single Pulsed Avalanche Energy (Note 2)	E_{AS}	250		mJ
Repetitive Avalanche Energy (Note 1)	E_{AR}	14		mJ
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5		V/ns
Drain Power Dissipation	Tc=25	140	50	W
	Derate above 25	1.12	0.4	W/
Maximum Junction Temperature	T _j	150		
Storage Temperature Range	T _{stg}	-55 150		
Thermal Characteristics				
Thermal Resistance, Junction-to-Case	R _{thJC}	0.89	2.5	/W
Thermal Resistance, Case-to-Sink	R _{thCS}	0.5	-	/W
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5	62.5	/W

* : Drain current limited by maximum junction temperature.

PIN CONNECTION



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ELECTRICAL CHARACTERISTICS (T_c=25 °C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250 μA, V _{GS} =0V	200	-	-	V
Breakdown Voltage Temperature Coefficient	BV _{DSS} /T _j	I _D =250 μA, Referenced to 25	-	0.18	-	V/°C
Drain Cut-off Current	I _{DSS}	V _{DS} =200V, V _{GS} =0V,	-	-	10	μA
Gate Threshold Voltage	V _{th}	V _{DS} =V _{GS} , I _D =250 μA	2	-	4	V
Gate Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
Drain-Source ON Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =9.5A	-	0.14	0.18	
Dynamic						
Total Gate Charge	Q _g	V _{DS} =160V, I _D =19A V _{GS} =10V (Note4,5)	-	35	44	nC
Gate-Source Charge	Q _{gs}		-	4.8	-	
Gate-Drain Charge	Q _{gd}		-	18	-	
Turn-on Delay time	t _{d(on)}	V _{DD} =100V R _L =5 R _G =25 (Note4,5)	-	12	30	ns
Turn-on Rise time	t _r		-	33	70	
Turn-off Delay time	t _{d(off)}		-	130	270	
Turn-off Fall time	t _f		-	75	160	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	900	1170	pF
Reverse Transfer Capacitance	C _{rss}		-	213	277	
Output Capacitance	C _{oss}		-	80	104	
Source-Drain Diode Ratings						
Continuous Source Current	I _S	V _{GS} <V _{th}	-	-	19	A
Pulsed Source Current	I _{SP}		-	-	76	
Diode Forward Voltage	V _{SD}	I _S =19A, V _{GS} =0V	-	-	1.5	V
Reverse Recovery Time	t _{rr}	I _S =19A, V _{GS} =0V, dI _S /dt=100A/μs	-	215	-	ns
Reverse Recovery Charge	Q _{rr}		-	2	-	μC

Note 1) Repetivity rating : Pulse width limited by junction temperature.

Note 2) L =1mH, I_S=19A, V_{DD}=50V, R_G=25 Ω, Starting T_j=25 °C.

Note 3) I_S 19A, dI/dt 200A/μs, V_{DD} BV_{DSS}, Starting T_j=25 °C.

Note 4) Pulse Test : Pulse width 300μs, Duty Cycle 2%.

Note 5) Essentially independent of operating temperature.

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Fig1. $I_D - V_{DS}$

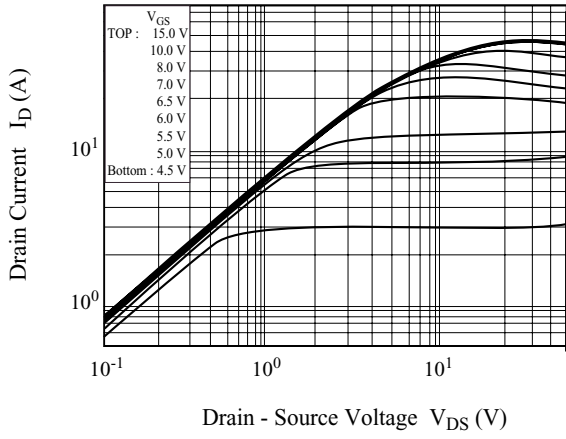


Fig2. $I_D - V_{GS}$

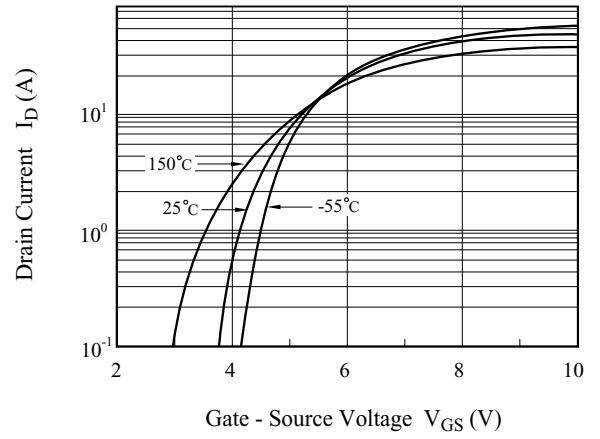


Fig3. $BV_{DSS} - T_j$

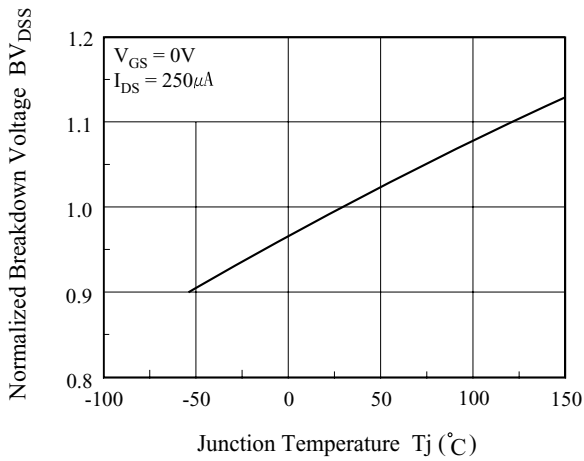


Fig4. $R_{DS(ON)} - I_D$

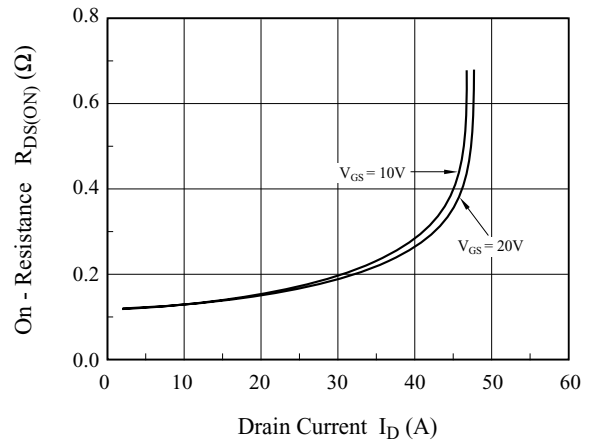


Fig5. $I_S - V_{SD}$

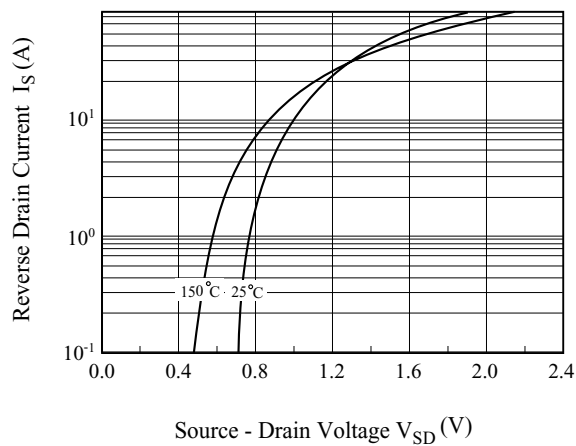
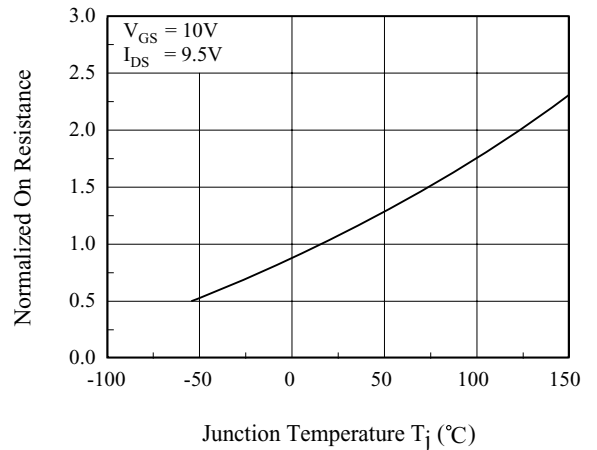


Fig6. $R_{DS(ON)} - T_j$



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Fig7. C - V_{DS}

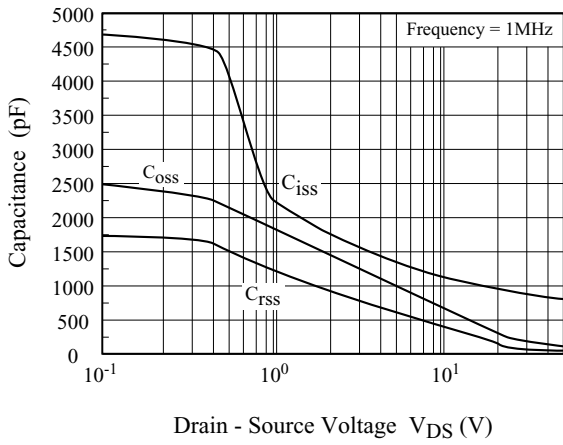


Fig8. Q_g - V_{GS}

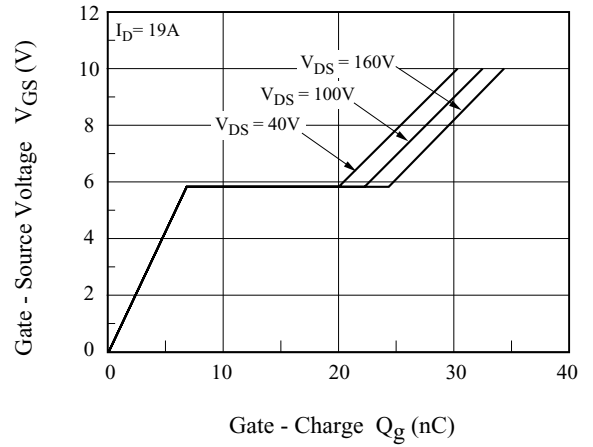


Fig9. Safe Operation Area

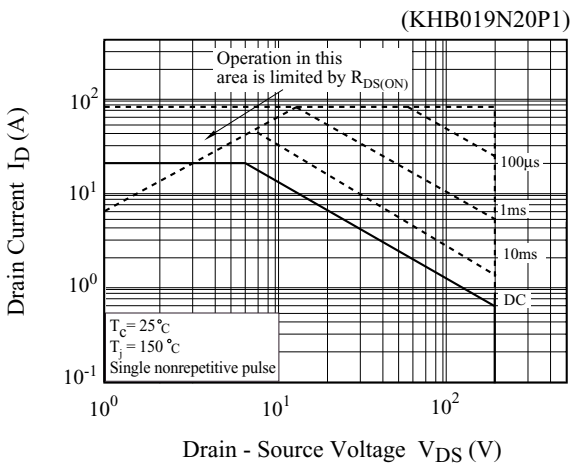


Fig10. Safe Operation Area

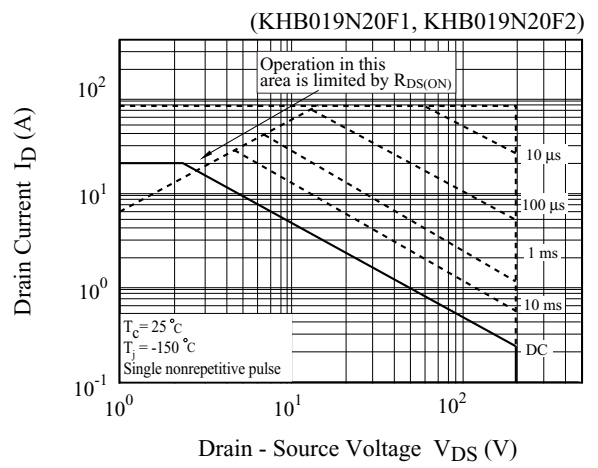
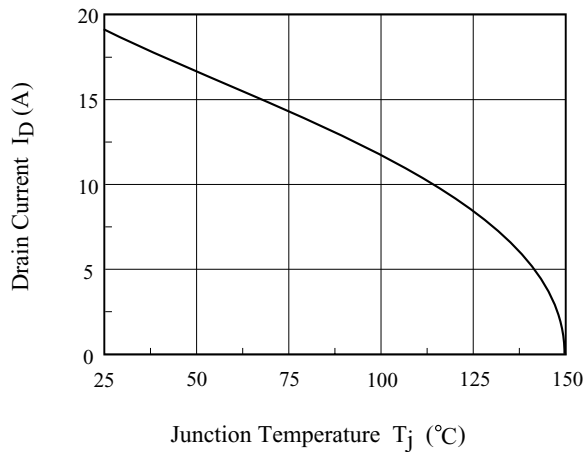


Fig11. I_D - T_j



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Fig12. Transient Thermal Response Curve

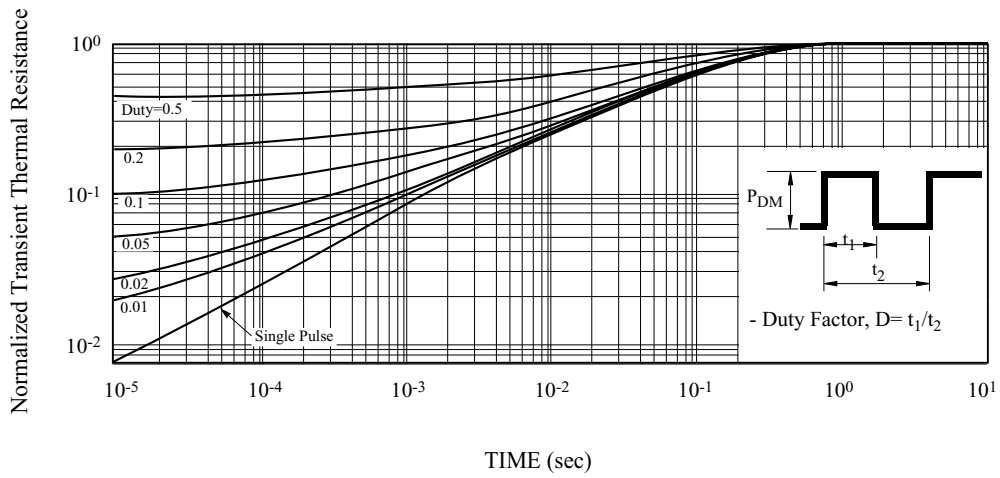


Fig13. Transient Thermal Response Curve

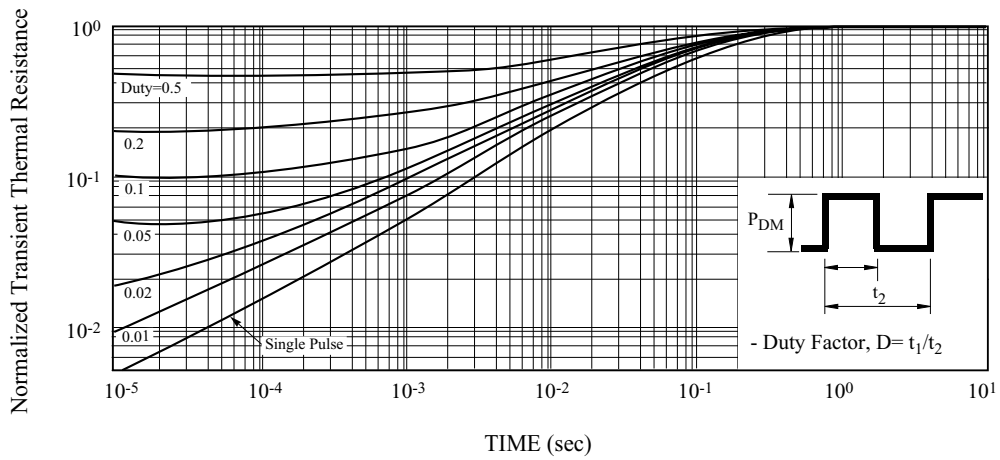


Fig14. Gate Charge

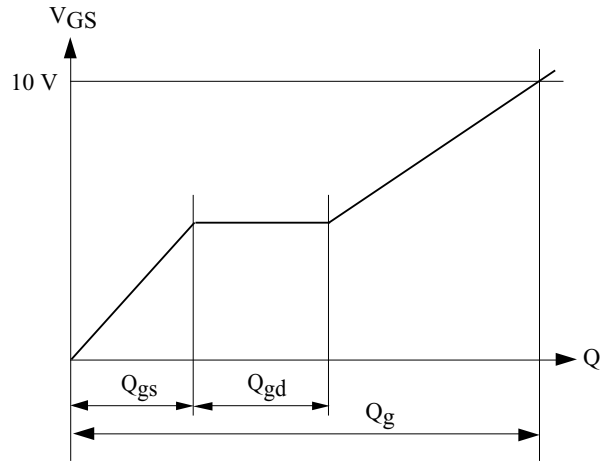
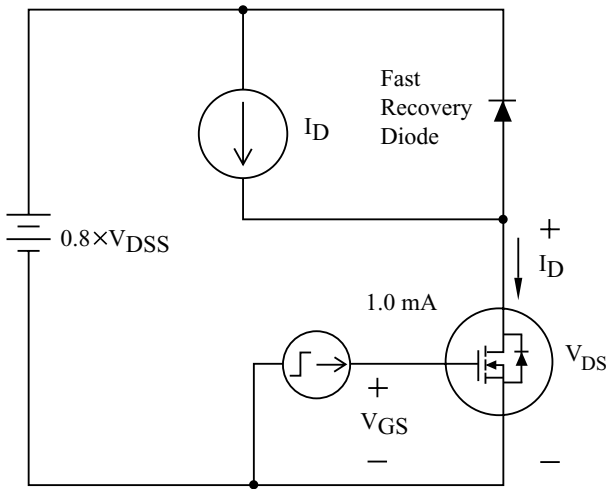
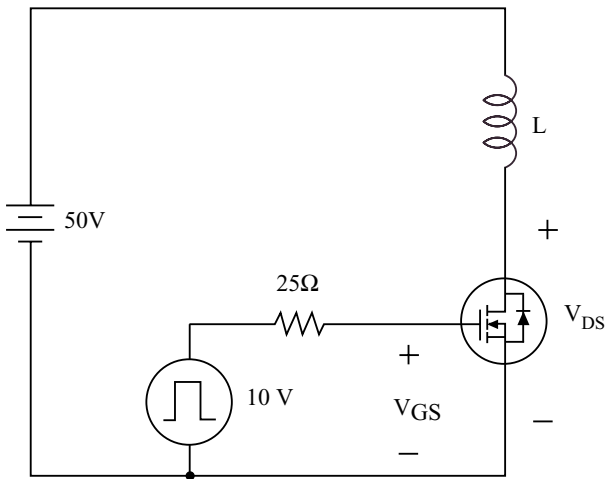


Fig15. Single Pulsed Avalanche Energy



$$E_{AS} = \frac{1}{2} L I_{AS}^2 \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

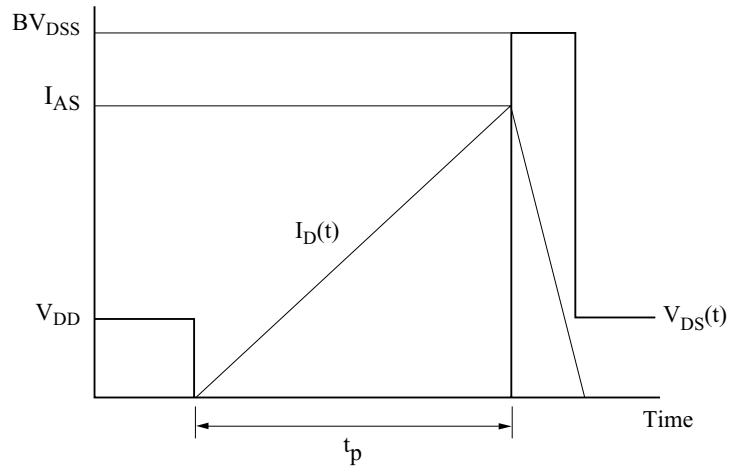
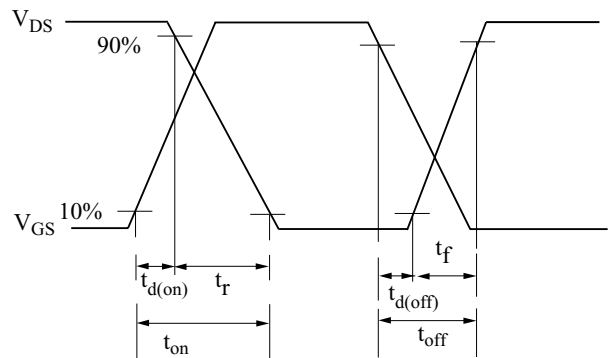
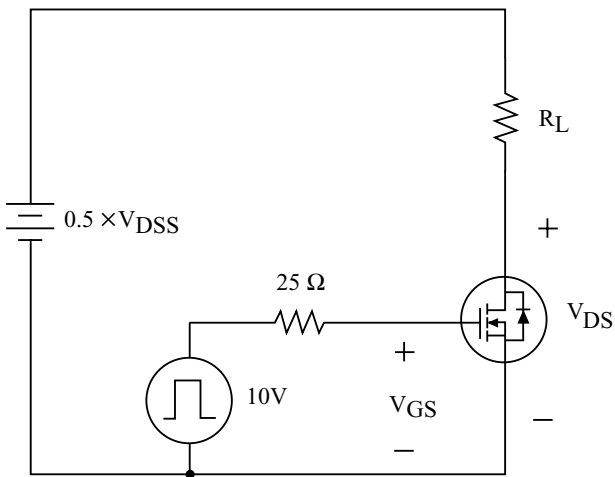


Fig16. Resistive Load Switching



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Fig17. Source - Drain Diode Reverse Recovery and dv/dt

